

ABSTRACT OF THE DISCLOSURE

The present invention provides an apparatus combining a high-speed high-precision characteristic
5 equivalent to that of a die bonder and a flexibility of coping quickly with a process variation and product variation along with size reduction and economics. This apparatus comprises a base unit including a body containing a device to be used in common among a plurality of processes
10 for mounting and assembling parts, a mechanism for conveying a workpiece in a predetermined conveying direction and a mechanism for positioning the workpiece, a dedicated unit including an end effector, and a selected mechanism unit including a mechanism for moving the end
15 effector in two axial directions perpendicular to the predetermined conveying direction to adjust a relative position between the end effector and the workpiece or a part. The moving mechanism is interchangeably attached on the base unit, and the end effector is interchangeably
20 attached on the moving mechanism.